

# **Description**

The VST05P076 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{\text{DS(ON)}}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

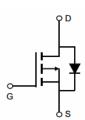
#### **General Features**

- $V_{DS}$  =-50V, $I_D$  =-80A  $R_{DS(ON)}$ =7.6m $\Omega$  (typical) @  $V_{GS}$ =-10V
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

#### **Application**

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification





Schematic Diagram

### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST05P076-TC	VST05P076	TO-220C	-	-	-

Absolute Maximum Ratings (T<sub>c</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	-50	V	
Gate-Source Voltage	V <sub>G</sub> s	±20	V	
Drain Current-Continuous	I <sub>D</sub>	-80	А	
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100°C)	-56.5	Α	
Pulsed Drain Current	I <sub>DM</sub>	-320	Α	
Maximum Power Dissipation	P <sub>D</sub>	180	W	
Derating factor		1.2	W/°C	
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	1024	mJ	
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	$^{\circ}$ C	

#### **Thermal Characteristic**

Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	$R_{ heta JC}$	0.83	°C/W

Shenzhen VSEEI Semiconductor Co., Ltd

# Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

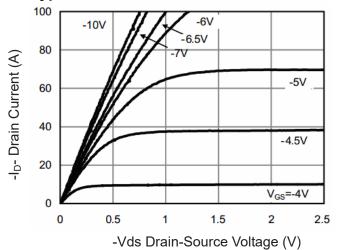
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	•		•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-50		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-50V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=-250\mu A$	-1.5	-2.5	-3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-40A	-	7.6	9	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V,I <sub>D</sub> =-40A	-	35	-	S
Dynamic Characteristics (Note4)	<u>.</u>					
Input Capacitance	C <sub>lss</sub>	\/ - 25\/\/ -0\/	-	2636	-	PF
Output Capacitance	Coss	$V_{DS}$ =-25V, $V_{GS}$ =0V, F=1.0MHz	-	1155	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	r-1.0IVInz	-	22	-	PF
Switching Characteristics (Note 4)	<u>.</u>					
Turn-on Delay Time	t <sub>d(on)</sub>		-	12.5	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-25V, $I_D$ =-40A $V_{GS}$ =-10V, $R_G$ =1.6 $\Omega$	-	10	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	35	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	8	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =-25V,I <sub>D</sub> =-40A,	-	31.2	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ 25 $V_{ID}$ 40A, $V_{GS}$ 10V	-	9.4	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	VGS10V	-	7.5	-	nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-40A	-		-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-80	Α
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> =-40A	-	30	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	75	-	nC

# Notes:

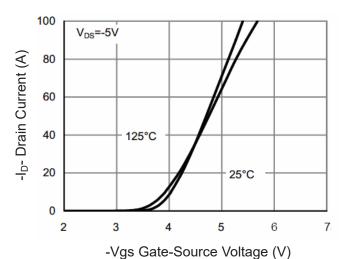
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25  $^{\circ}\text{C}$  ,V\_DD=-25V,V\_G=-10V,L=0.5mH,Rg=25 $\Omega$



## **Typical Electrical and Thermal Characteristics**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

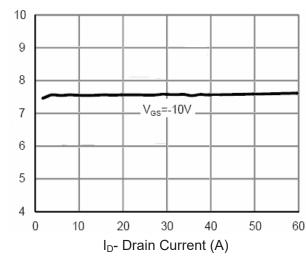


Figure 3 Rdson-Drain Current

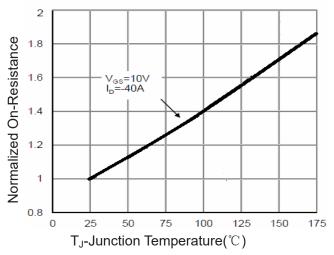


Figure 4 Rdson-JunctionTemperature

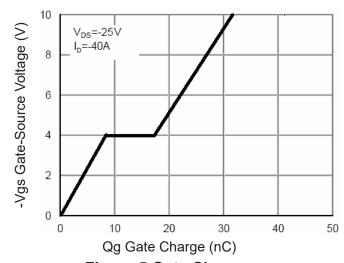


Figure 5 Gate Charge

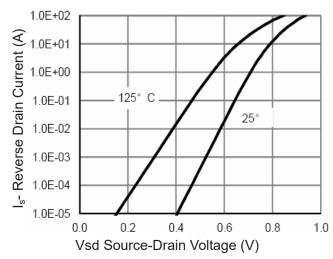


Figure 6 Source- Drain Diode Forward



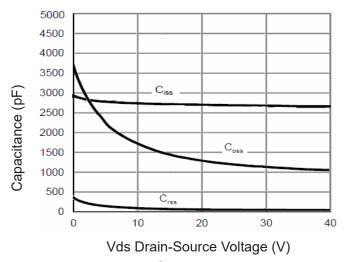


Figure 7 Capacitance vs Vds

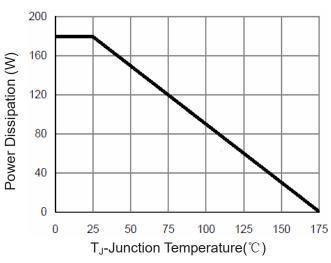


Figure 9 Power De-rating

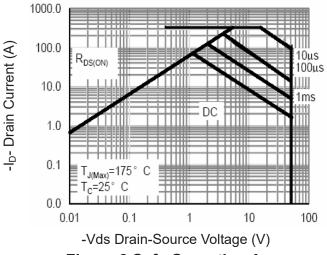


Figure 8 Safe Operation Area

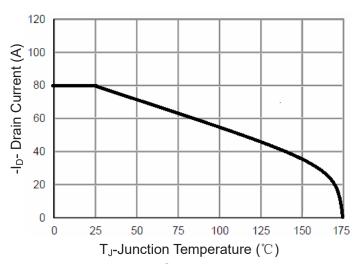


Figure 10 Current De-rating

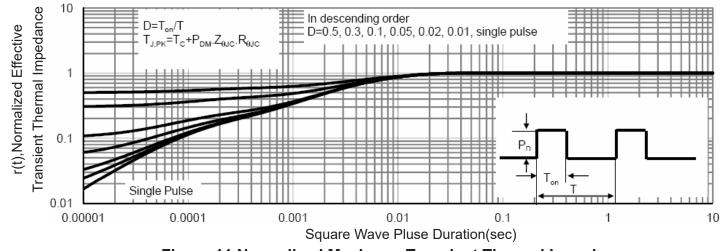


Figure 11 Normalized Maximum Transient Thermal Impedance